

Vogt AG Verbindungstechnik creating connections



SMD PRODUCT RANGE

Contact springs

Screw fixings

Solder bridges




Fuse holders

Mating plugs

SMD contact springs

Product	Designation	Material	Surface	Packing unit
	400.20 SMD contact springs	Beryllium copper	blank	Bags (250 units)
	400.22 SMD contact springs	Beryllium copper	Gold-plated	Bags (250 units)
	400.80 SMD contact springs	Stainless steel	blank	Bags (250 units)
	400.82 SMD contact springs	Stainless steel	Gold-plated	Bags (250 units)

SMD screw fixings

Product	Designation	Material	Surface	Packing unit
	408.60 SMD screw fixing	Brass	blank	Bags (500 units)
	408.68 SMD screw fixing	Brass	pure tin-plated	Bags (500 units)
	408068 SMD screw fixing	Brass	pure tin-plated	Taped (500 units)




SMD solder bridges

Product	Designation	Material	Surface	Packing unit	
	410.48	SMD solder bridges	Copper	pure tin-plated	Bags (250 units)

SMD fuse holders

Product	Designation	Material	Surface	Packing unit	
	420.28	SMD fuse holders	Bronze	pure tin-plated	Bags (1000 units)
	4200.28	SMD fuse holders	Bronze	pure tin-plated	Taped (1000 units)

SMD mating plugs

Product	Designation	Material	Surface	Packing unit	
	450.60	SMD mating plugs	Brass	blank	Bags (500 units)
	450.64	SMD mating plugs	Brass	Tin-plated reflow	Bags (500 units)
	4500.64	SMD mating plugs	Brass	Tin-plated reflow	Taped (500 units)

Blister packs of SMD components

Due to the increasing fully-automated assembly of circuit boards, we have expanded SMD's range of parts and adapted it to market needs. Once manufactured and finished, these parts are placed in transparent packaging without damaging the product.

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SMD

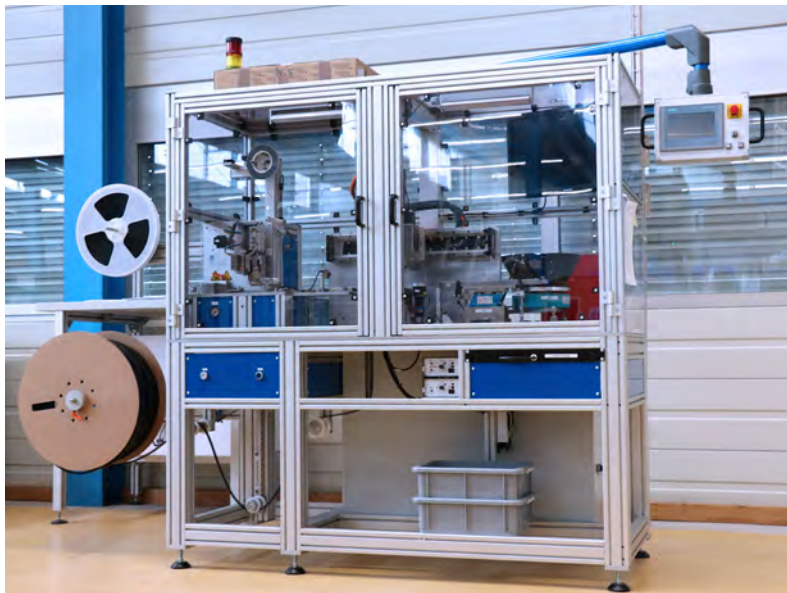
Cost-effective and gentle processing

SMD stands for Surface Mounted Devices, a surface-mounted component of an electronics printed circuit board. Particularly small components are processed gently and cost-effectively with this technology. While several steps are needed for conventional Through-Hole Technology (THT), the SMD component is placed directly on a copper-clad surface of the board and soldered.

The direct surface mounting enables processing on both sides and can easily be installed in small, compact enclosures such as mobile telephones or medical devices. Additional costs can be saved with the elimination of the drilling and the resulting faster production.

Blister

New opportunities



Vogt AG uses a variety of blister machines. The latest generation of machines allows packages of varying sizes and even smaller quantities to be packed by machine. A camera unit can be used to check the correct position of asymmetrical parts if required.

